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PALPILOT

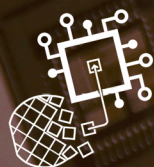
PACKAGING SYSTEMS

INFRASTRUCTURE SOLUTIONS



PACKAGE DESIGN

- Package Structure Definition (2.5D PoP, embedded, FC.WB)
- Electronic Schematic
- Substrate Routing
- SI/PI Modeling



PACKAGING ASSEMBLY

- 2.5D SiP
- PoP Configuration
- High Power / Frequency Systems
- Optical / VCSEL / PD



SUBSTRATE FABRICATION

- Ceramic: High Power (Al_2O_3 , AlN, BeO)
- Laminate (BT, coreless, high density)
- Low Dk/Df Polyimide (Df = 0.004)



TESTING

- Functional E-Test
- Optical (far / near field)
- Reliability (accelerated life testing)

NPI TO HIGH VOLUME

Product Life Cycle Solutions
Miniaturization
56 GBit+
Thermal Solutions

INDUSTRY CERTIFIED

- ✓ Automotive
- ✓ Medical
- ✓ Commercial
- ✓ IoT